

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20200124000.1A Qualification of TI Malaysia an additional Assembly and Test site for Select Devices Change Notification / Sample Request

Date: March 18, 2020

To: PREMIER FARNELL PCN

Dear Customer:

Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

20200124000.1A Change Notification / Sample Request Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

CUSTOMER PART NUMBER

MSP430FR2422IPW16 MSP430FR2512IPW16 MSP430FR2522IPW16

null null null

Technical details of this Product Change follow on the next page(s).

PCN Number: 20200124000.1A						D	CN D	ate: Mar 18, 202	20			
, ,						St Site	e for Select Devices	,				
Customer Contact: PCN Manager				Dep)T:	Quality Serv			Data musidad at			
Pr	oposed 1 st S	Ship D	ate:	Apr 30	2020		Estimated Sample Availability:			Date provided at sample request		
Change Type:												
\boxtimes	Assembly S	Site			Des	Design Wafer Bump Site						
	Assembly F	rocess	5		Dat	Data Sheet			Wafer Bump Material			
	Assembly N	Materia	als			Part number change			Wafer Bump Process			
	Mechanical Specification			Test Site			Wafer Fab Site					
	Packing/Shipping/Labeling		Tes	est Process			Wafer Fab Materials					
						☐ Wafer Fab Process			r Fab Process			
	PCN Details											
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										ice list below. The		
										notice (June 18,		
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ap	plies for the o	origina	ıl set o	f device	es.							
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Re	Reason for Change:											
Со	ntinuity of Si	upply										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):												
None												
Anticipated impact on Material Declaration												
Material Declaration from			rom production data and will be available following the									
			production release. Upon production release the revised reports can be obtained at the site link below									
					•							
http://www.ti.com/quality/docs/materialcontentsearch.tsp							ntentsearch.tsp					
Changes to product identification resulting from this PCN:												
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			bly Site Origin (22L)		Asser	nbly Country Co (23L)	de		Assembly City			
	TI Mexico MEX			MEX				Aguascalientes				
	TI Taiwan TAI			TWN			Chung Ho					
ا ٍ ا	TI Malaysia MLA				MYS		Kuala Lumpur					
Sa	Sample product shipping label (not actual product label)											

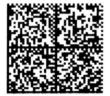
TEXAS INSTRUMENTS

MADE IN: Malaysia 2DC: 20:

MSL 2 /260C/1 YEAR SEAL DT 1 /235C/UNLIM 03/29/04

OPT: ITEM:

(L)T0:3750



(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2

(P) (2P) REV:

(20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MVC (23L) ACO: MYS

Product Affected:

MSP430FR2422IPW16	TCAN1042HD	TCAN1042HVD	TCAN1051HGVD
MSP430FR2422IPW16R	TCAN1042HDR	TCAN1042HVDR	TCAN1051HGVDR
MSP430FR2512IPW16	TCAN1042HGD	TCAN1051HD	TCAN1051HVD
MSP430FR2512IPW16R	TCAN1042HGDR	TCAN1051HDR	TCAN1051HVDR
MSP430FR2522IPW16	TCAN1042HGVD	TCAN1051HGD	
MSP430FR2522IPW16R	TCAN1042HGVDR	TCAN1051HGDR	



TI Information Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TCAN1051DQ1	Qual Device: TCAN1042DQ1	Qual Device: TCAN1042HVDQ1	Qual Device: TCAN1051VDQ1
AC	Autoclave 121C	96 Hours	-	1/77/0	1/77/0	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	1/77/0	1/77/0
HTOL	Life Test, 150C	300 Hours	-	1/77/0	1/77/0	1/77/0
HTSL	High Temp Storage Bake 175C	500 Hours	-	1/45/0	1/45/0	1/45/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	1/77/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	1/30/0	1/30/0	1/30/0	1/30/0
WBS	Wire Bond Shear	Wires	1/30/0	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Devices TCAN1042DQ1, TCAN1051VDQ1, TCAN1051DQ1 and TCAN1042HVDQ1 are qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV, 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Results

Approved: 04-Mar-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: MSP430FR2522IPW16
AC	Autoclave 121C	96 Hours	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/77/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
WBP	Bond Pull	Wires	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0

- QBS: Qualification By Similarity
- Qualification Device MSP430FR2522IPW16 is qualified at Moisture Sensitivity LEVEL2-260C.
- Preconditioning was performed for Autoclave, Biased HAST, Temperature Cycle, and HTSL.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

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